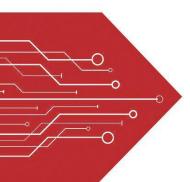
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet



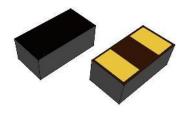
Features

Ultra-Low capacitance:0.05pF(typ.)
Low leakage current(<10nA)
Fast response time(<1ns)
Bi-directional,single line protection
IEC 61000-4-2 (ESD Air): 15kV
IEC 61000-4-2 (ESD Contact): 8kV

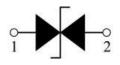
Applications

USB 3.0/3.1 HDMI 1.3/1.4/2.0 RF Antenna SATA and eSATA Interface

Pin Description



Schematic Diagram



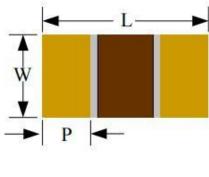
Limiting Values($T_A = 25$ °C, unless otherwise specified)

Symbol	Parameter	Conditions		Max	Unit
V 5 1 1 1 5 1 1 1 1 1 1 1 1 1 1 1 1 1 1		IEC 61000-4-2; Contact Discharge		8	kV
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Air Discharge	-	15	kV
T _A	Operating Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-40	85	°C

Electrical Characteristics(T_A = 25 °C unless otherwise specified)

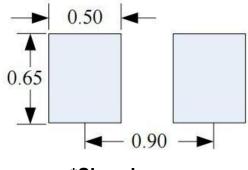
Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
V _{DC}	Continuous Operating Voltage	-	-	-	18	٧
V _T	Trigger Voltage	IEC61000-4-2 8kV contact	-	450	-	V
		discharge				
\/ ₋	Clamping Valtage	IEC61000-4-2 8kV contact	-	40	-	V
V _C Clamp	Clamping Voltage	discharge				
	Leakage Current	DC 5V shall be applied	-	-	10	nA
IL.	Leakage Current	on component				
CJ	Capacitance	Measured at 10MHz	_	0.05	-	pF







Recommended Solder Pad Footprint



*Sizes in mm

Notes:

This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters		
	Min.	Max.	
L	0.90	1.10	
W	0.42	0.62	
р	0.15	0.35	
Н	0.25	0.45	

REEL SPECIFICATION

P/N	PKG	QTY
PESD18VF1BLYL-MS	SOD-882	10000



Semiconductor

Compiance

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